



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Park et al.

Docket No.: TI-35623

Serial No.: 10/628,198

Art Unit: 2814

Filed: 07/28/2003

Examiner: Peralta, Ginette

Title: A Two-Step Semiconductor Manufacturing Process For Copper
Interconnects

AMENDMENT UNDER 37 C.F.R. §1.111

December 2, 2004

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Commissioner:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited
with the U.S. Postal Service on 12-2-04
as First Class Mail in an envelope addressed to: Commissioner for
Patents, P.O. Box 1450, Alexandria, VA 22313-1450

Karen Vertz
Karen Vertz

12-2-04
Date

In response to the Office Action, dated 08/13/2004, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Please charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.